



Material Content Data Sheet



Sales Product Name				IPP410N30N		Issued		20. July 2018	
MA#				MA001158662					
Package				PG-TO220-3-1		Weight*		2044.22 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	17.562	0.86	0.86	8591	8591	
leadframe	non noble metal	iron	7439-89-6	0.816	0.04		399		
	inorganic material	phosphorus	7723-14-0	0.245	0.01		120		
	non noble metal	copper	7440-50-8	815.335	39.88	39.93	398850	399369	
wire	non noble metal	aluminium	7429-90-5	11.072	0.54	0.54	5416	5416	
encapsulation	organic material	carbon black	1333-86-4	8.656	0.42		4234		
	plastics	epoxy resin	-	95.212	4.66		46576		
	inorganic material	silicondioxide	60676-86-0	473.177	23.15	28.23	231471	282281	
leadfinish	non noble metal	tin	7440-31-5	21.462	1.05	1.05	10499	10499	
plating	non noble metal	nickel	7440-02-0	0.244	0.01		119		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	398849	119	
solder	noble metal	silver	7440-22-4	0.255	0.01		125		
	non noble metal	tin	7440-31-5	0.204	0.01		100		
	non noble metal	lead	7439-92-1	9.743	0.48	0.50	4766	4991	
heatspreader	non noble metal	iron	7439-89-6	0.590	0.03		289		
	inorganic material	phosphorus	7723-14-0	0.177	0.01		87		
	non noble metal	copper	7440-50-8	589.466	28.84	28.88	288358	288734	
*deviation	< 10%					Sum in total:	100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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